

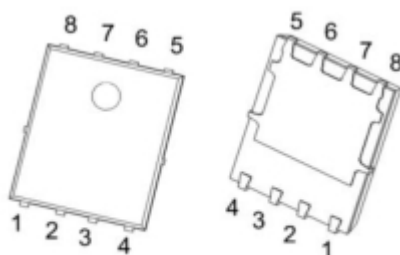
Product Summary

$V_{(BR)DSS}$	$R_{DS(on)TYP}$	I_D
-30V	7.5m Ω @-10V	-45A
	11m Ω @-4.5V	

Feature

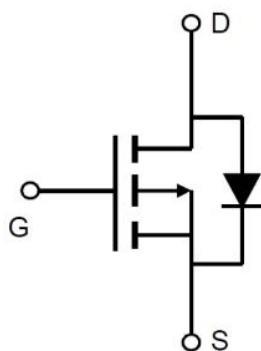
- Enhancement mode
- Low on-resistance $R_{DS(on)}$
- Pb-free lead plating; RoHS compliant

Package

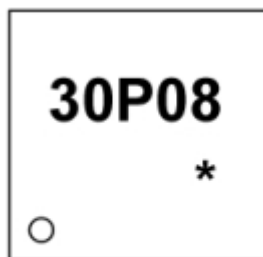


PDFN5X6-8L

Circuit diagram



Marking



30P08 =Device Code
* =Week Code

Absolute maximum ratings

(T_a=25°C unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V _{DS}	-30	V
Gate-Source Voltage	V _{GS}	±20	V
Continuous Drain Current(T _C = 25°C)	I _D	-45	A
Pulsed Drain Current ¹	I _{DM}	-180	A
Single Pulsed Avalanche Energy ²	E _{AS}	140	mJ
Power Dissipation(T _C = 25°C)	P _D	32	W
Thermal Resistance, Junction to Case	R _{θJC}	3.9	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Electrical characteristics

($T_A=25^{\circ}\text{C}$, unless otherwise noted)

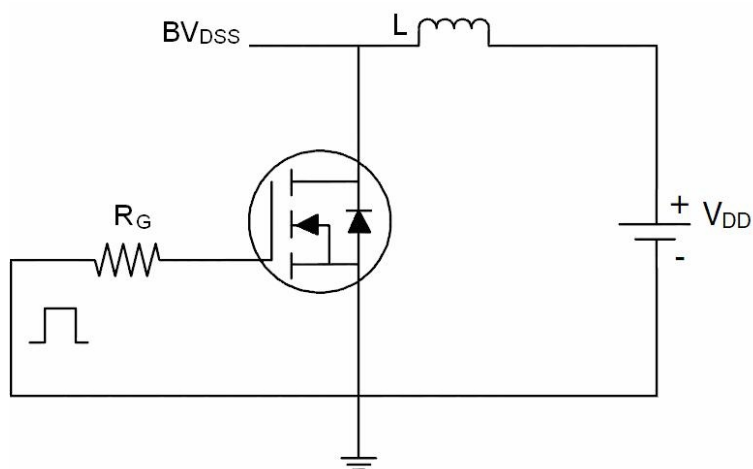
Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	BV (BR)DSS	V _{GS} = 0V, I _D = -250μA	-30			V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = -30V, V _{GS} = 0V			-1	uA
Gate-Source Leakage	I _{GSS}	V _{GS} = ±20V, V _{DS} =0V			±100	uA
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D = -250μA	-1	-1.6	-2.5	V
Static Drain-Source on-Resistance	R _{DS(on)}	V _{GS} = -10V, I _D = -20A		7.5	10	mΩ
		V _{GS} = -4.5V, I _D = -10A		11	15	
Dynamic Characteristics						
Input Capacitance	C _{iss}	V _{DS} = -15V, V _{GS} =0V, f=1MHz		3459		pF
Output Capacitance	C _{oss}			427		
Reverse Transfer Capacitance	C _{rss}			394		
Total Gate Charge	Q _g	V _{DS} = -15V, I _D = -40A, V _{GS} = -10V		37		nC
Gate-Source Charge	Q _{gs}			6.5		
Gate-Drain Charge	Q _{gd}			9.4		
Switching Characteristics						
Turn-on Delay Time	T _{d(on)}	V _{DD} = -15V, I _D = -20A, V _{GS} = -10V, R _{GEN} =2.5Ω		16		nS
Turn-on Rise Time	T _r			21		
Turn-off Delay Time	T _{d(off)}			68		
Turn-off Fall Time	T _f			52		
Drain-Source Diode Characteristics						
Maximum Continuous Drain to Source Diode Forward Current	I _S				-40	A
Maximum Pulsed Drain to Source Diode Forward Current	I _{SM}				-160	A
Drain to Source Diode Forward Voltage	V _{SD}	V _{GS} =0V,I _S = -40A		-0.8	-1.2	V

Note:

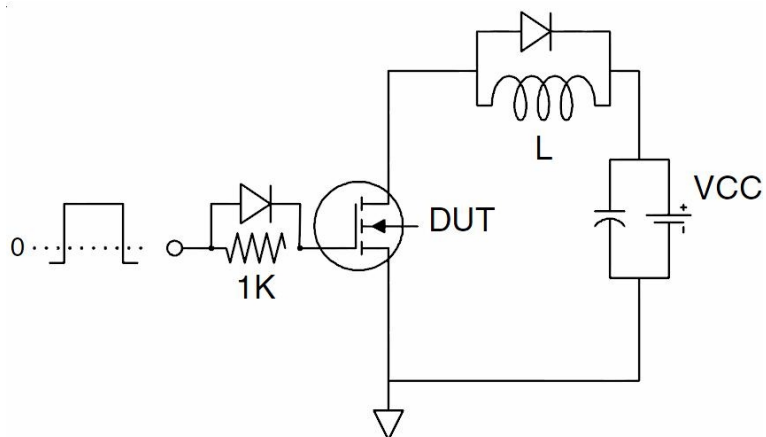
1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature
2. E_{AS} condition: $T_J = 25^{\circ}\text{C}$, $V_{DD} = -15V$, $V_G = -10V$, $L = 0.5mH$, $R_G = 25\Omega$, $I_{AS} = -20A$
3. Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$

Test Circuit

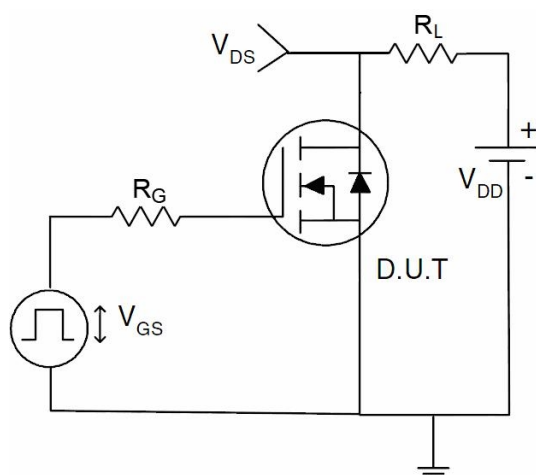
- EAS Test Circuits



- Gate Charge Test Circuit



- Switch Time Test Circuit



Typical Characteristics

Figure 1: Output Characteristics

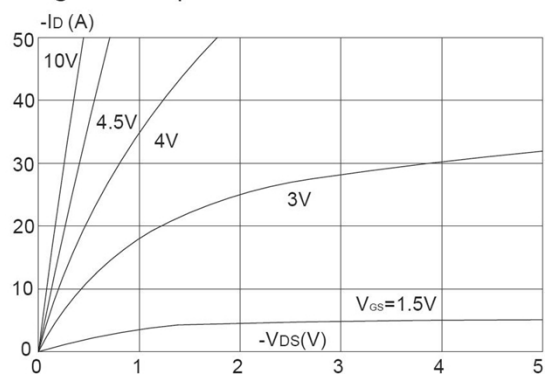


Figure 2: Typical Transfer Characteristics

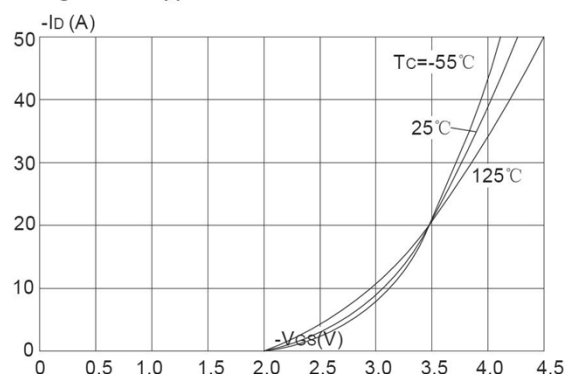


Figure 3: On-resistance vs. Drain Current

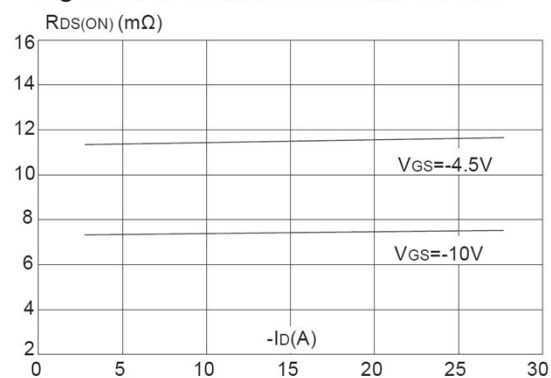


Figure 4: Body Diode Characteristics

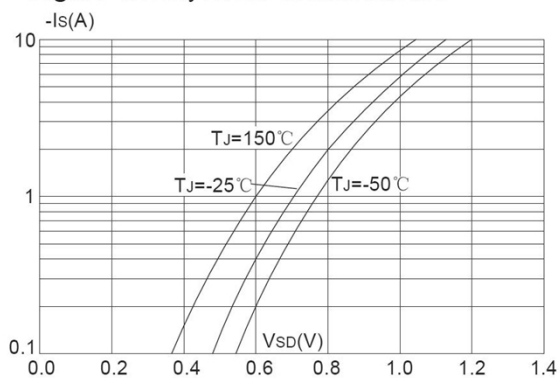


Figure 5: Gate Charge Characteristics

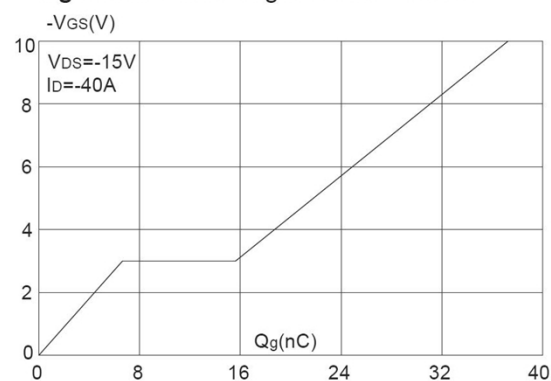


Figure 6: Capacitance Characteristics

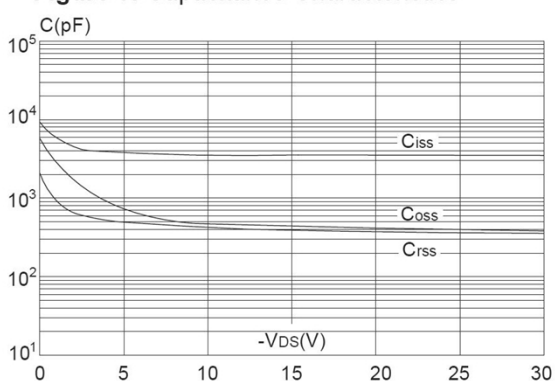


Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

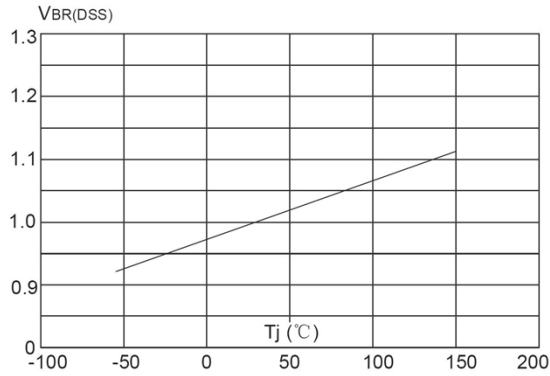


Figure 8: Normalized on Resistance vs. Junction Temperature

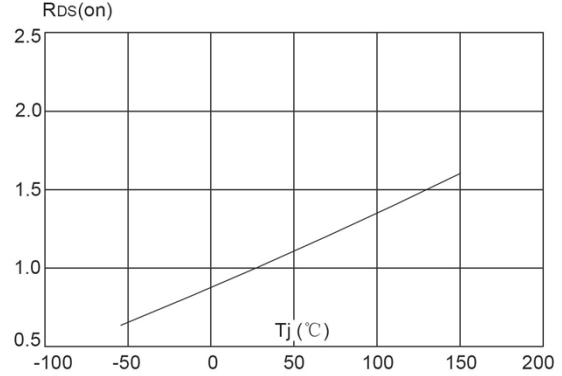


Figure 9: Maximum Safe Operating Area

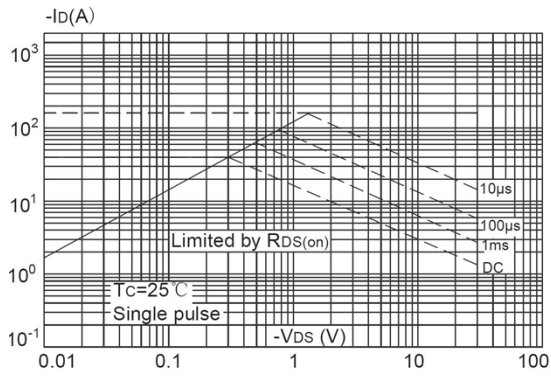


Figure 10: Maximum Continuous Drain Current vs. Case Temperature

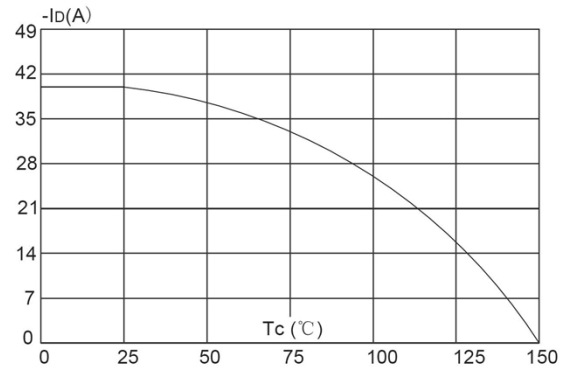
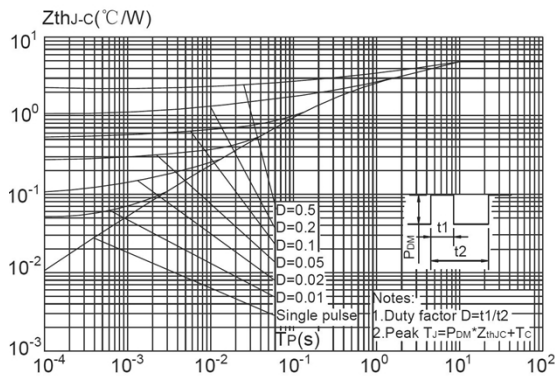
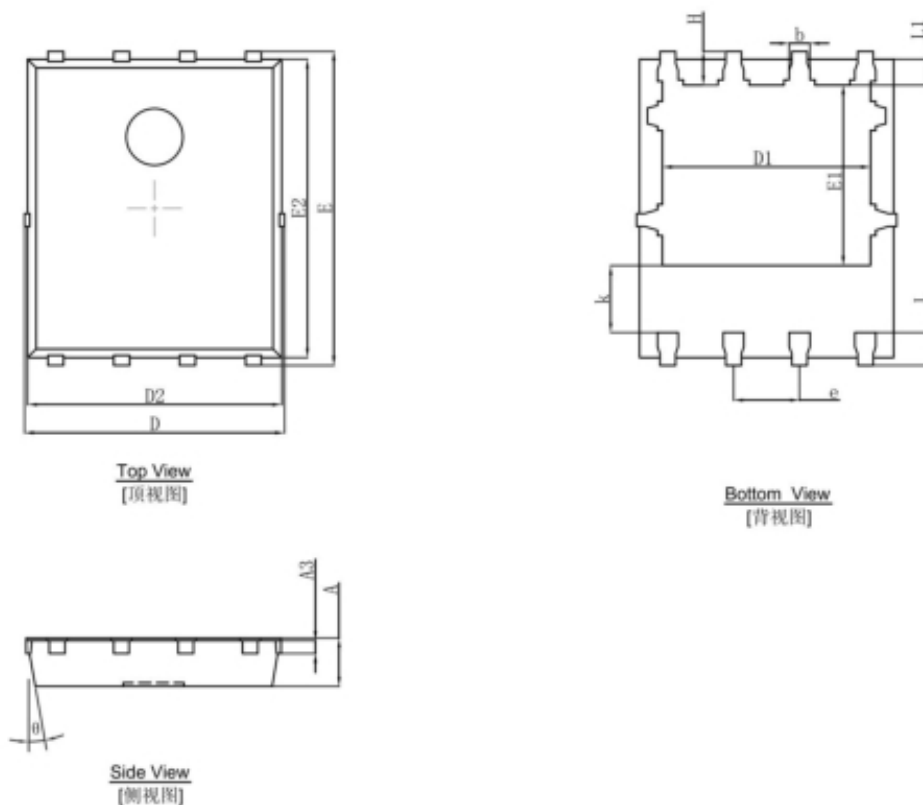


Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Case



PDFN5X6-8L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.000	0.035	0.039
A3	0.254REF.		0.010REF.	
D	4.944	5.096	0.195	0.201
E	5.974	6.126	0.235	0.241
D1	3.910	4.110	0.154	0.162
E1	3.375	3.575	0.133	0.141
D2	4.824	4.976	0.190	0.196
E2	5.674	5.826	0.223	0.229
k	1.190	1.390	0.047	0.055
b	0.350	0.450	0.014	0.018
e	1.270TYP.		0.050TYP.	
L	0.559	0.711	0.022	0.028
L1	0.424	0.576	0.017	0.023
H	0.574	0.726	0.023	0.029
θ	10°	12°	10°	12°